

In the Claims: (strikethrough parts deleted and underlined parts added)

Claims 18 and 19 have been withdrawn with Claim 17 being previously canceled.

1. (Currently Amended) A dry-wet thermal management system, comprising:
a chassis having a dry chamber ~~including a plurality of vents~~ and a spray chamber,
~~wherein said dry chamber is capable of receiving~~ at least one dry electronic card positioned
within said dry chamber and ~~wherein said spray chamber is capable of receiving~~ at least one
wet electronic card positioned within said spray chamber; and

a spray unit within said spray chamber for applying coolant to said at least one a wet
electronic card.

2. (Currently Amended) The dry-wet thermal management system of Claim 1, wherein
said dry chamber includes a fan for forcing air over ~~a~~ said at least one dry electronic card.

3. (Original) The dry-wet thermal management system of Claim 1, including:
a first opening within a rear portion of said chassis extending into said spray chamber;
a second opening within said rear portion of said chassis extending into said dry chamber;
and

a main backplane attached to said rear portion of said chassis, wherein said main
backplane has at least one dry socket extending into said dry chamber and at least one wet socket
extending into said spray chamber.

4. (Original) The dry-wet thermal management system of Claim 3, wherein said main
backplane is sealed to said rear portion of said chassis about said first opening and said second
opening.

5. (Original) The dry-wet thermal management system of Claim 4, including a seal
positioned between said rear portion of said chassis and said main backplane.

6. (Original) The dry-wet thermal management system of Claim 5, wherein said seal is comprised of a single structure.

7. (Original) The dry-wet thermal management system of Claim 5, wherein said seal is comprised of a first seal surrounding said first opening and a second seal surrounding said second opening.

8. (Original) The dry-wet thermal management system of Claim 4, including a sealant positioned between said rear portion of said chassis and said main backplane.

9. (Original) The dry-wet thermal management system of Claim 1, including a spray cooling management unit fluidly connected to said spray unit and said spray chamber.

10. (Original) The dry-wet thermal management system of Claim 1, including:
a first opening within a rear portion of said chassis extending into said spray chamber;
a second opening within said rear portion of said chassis extending into said dry chamber;
a main backplane attached to said rear portion of said chassis, wherein said main backplane has at least one dry socket extending into said dry chamber; and
a secondary backplane attached to said rear portion of said chassis and electrically coupled to said main backplane, wherein said secondary backplane has at least one wet socket extending into said spray chamber.

11. (Original) The dry-wet thermal management system of Claim 10, including a connector member electrically positioned between said main backplane and said secondary backplane.

12. (Original) The dry-wet thermal management system of Claim 10, wherein said secondary backplane and said main backplane are sealed to said rear portion of said chassis about said first opening and said second opening respectively.

13. (Original) The dry-wet thermal management system of Claim 12, including a seal positioned between said rear portion of said chassis and said main backplane and said secondary backplane.

14. (Original) The dry-wet thermal management system of Claim 13, wherein said seal is comprised of a single structure.

15. (Original) The dry-wet thermal management system of Claim 13, wherein said seal is comprised of a first seal surrounding said first opening and a second seal surrounding said second opening.

16. (Original) The dry-wet thermal management system of Claim 12, including a sealant positioned between said rear portion of said chassis and said main backplane.

17. (Canceled)

18. (Withdrawn) A method of utilizing a thermal management chassis having a dry chamber and a wet chamber, said method comprising the steps of:

- (a) positioning at least one high heat flux card within said wet chamber;
- (b) positioning at least one low heat flux card within said dry chamber;
- (c) applying liquid coolant upon said high heat flux card; and
- (d) applying airflow upon said low heat flux card.

19. (Withdrawn) The method of utilizing a thermal management chassis of Claim 18, wherein said high heat flux card and said low heat flux card are electrically connected within sockets of a main backplane.

20. (Previously Added) A dry-wet thermal management system, comprising:

a chassis having a dry chamber and a spray chamber, wherein said dry chamber and said spray chamber are each capable of receiving at least one heat producing card;

a spray unit within said spray chamber for applying coolant to at least one heat producing card;

a first opening within a rear portion of said chassis extending into said spray chamber;

a second opening within said rear portion of said chassis extending into said dry chamber;

and

a backplane attached to said rear portion of said chassis, wherein said backplane has a plurality of sockets, with at least one of said sockets extending into said dry chamber and at least one of said sockets extending into said spray chamber.

21. (Previously Added) The dry-wet thermal management system of Claim 20, wherein said dry chamber includes a fan for forcing air over at least one heat producing card.

22. (Previously Added) The dry-wet thermal management system of Claim 20, wherein said backplane is sealed to said rear portion of said chassis about said first opening and said second opening.

23. (Previously Added) The dry-wet thermal management system of Claim 22, including a seal positioned between said rear portion of said chassis and said backplane.

24. (Previously Added) The dry-wet thermal management system of Claim 23, wherein said seal is comprised of a single structure.

25. (Previously Added) The dry-wet thermal management system of Claim 23, wherein said seal is comprised of a first seal surrounding said first opening and a second seal surrounding said second opening.

26. (Previously Added) The dry-wet thermal management system of Claim 22, including a sealant positioned between said rear portion of said chassis and said backplane.

27. (Previously Added) The dry-wet thermal management system of Claim 22, including a spray cooling management unit fluidly connected to said spray unit and said spray chamber.

28. (Previously Added) The dry-wet thermal management system of Claim 20, including a secondary backplane attached to said rear portion of said chassis and electrically coupled to said backplane, wherein said secondary backplane includes at least one socket extending into said spray chamber.

29. (Previously Added) The dry-wet thermal management system of Claim 28, including a connector member electrically positioned between said backplane and said secondary backplane.

30. (Previously Added) The dry-wet thermal management system of Claim 28, wherein said secondary backplane and said backplane are sealed to said rear portion of said chassis about said first opening and said second opening respectively.

31. (Previously Added) The dry-wet thermal management system of Claim 30, including a seal positioned between said rear portion of said chassis and said backplane and said secondary backplane.

32. (Previously Added) The dry-wet thermal management system of Claim 31, wherein said seal is comprised of a single structure.

33. (Previously Added) The dry-wet thermal management system of Claim 31, wherein said seal is comprised of a first seal surrounding said first opening and a second seal surrounding said second opening.

34. (Previously Added) The dry-wet thermal management system of Claim 30, including a sealant positioned between said rear portion of said chassis and said backplane.

35. (Previously Added) The dry-wet thermal management system of Claim 20, wherein said dry chamber includes a plurality of vents for allowing air to pass over at least one heat producing card.